# AMD Selects Lam's 2300TM Etch Series for Next-generation Logic and Flash

FREMONT, Calif., September 10, 2002—Lam Research Corporation (Nasdaq: LRCX) today announced that Advanced Micro Devices, Inc. (NYSE: AMD), Sunnyvale, Calif., has selected Lam's 2300 Etch Series to develop next-generation logic and flash processes.

The 2300 Exelan dielectric and 2300 Versys silicon etch systems will be employed for both front- and back-end etch applications for AMD's development efforts. The 2300 Etch Series was selected for its straightforward 200/300-mm scaling and superior etch technology. The equipment is installed at AMD's Submicron Development Center (SDC), which supplies next-generation technology to all AMD Fabs worldwide.

"The transition to 300-mm technology helps us offer even greater benefit to our customers," said Dr. Linton Salmon, director of Advanced Process Development for AMD. "During the transition, we need to move easily between 200- and 300-mm wafer sizes. We expect that the 2300 Etch Series equipment will enable developing 200-mm processes cost effectively followed by straightforward scaling to 300 mm."

"Being selected for AMD's next-generation etch processes validates the 2300 Etch Series' process versatility and advanced capability," said Ferdinand Seemann, Lam's vice president of North America Field Operations.

Examples of applications in development for both logic and flash at AMD include high-aspect-ratio contact (HARC) and low k etch. AMD will also be developing in situ processing for dual damascene to implement maximum cost reduction in the back-end.

This press release contains certain forward-looking statements that are subject to the Safe Harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements include those relating to AMD's future uses for Lam equipment, the ability to scale processes to larger wafer sizes, process developments, cost effectiveness and potential process applications, among others. Such statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, significance, value and effect including those risks detailed in documents filed with the Securities and Exchange Commission, and specifically the report on Form 10-K for the fiscal year ended June 30, 2002, which could cause actual results to vary from expectations. The company undertakes no obligation to update the information in this Press Release.

Lam Research Corporation is a leading supplier of wafer fabrication equipment and services to the world's semiconductor industry. Lam's common stock trades on the Nasdaq National Market under the symbol LRCX. The Company's World Wide Web address is http://www.lamrc.com.

---

https://newsroom.lamresearch.com/2002-09-10-AMD-Selects-Lams-2300TM-Etch-Series-for-Next-generation-Logic-and-Flash